

## Integrated Silicon Pressure Sensor On-Chip Signal Conditioned, Temperature Compensated and Calibrated

The MP3V5010 series piezoresistive transducers are state-of-the-art monolithic silicon pressure sensors designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This transducer combines advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure.

### Features

- 5.0% Maximum Error Over 0° to 85°C
- Ideally Suited for Microprocessor or Microcontroller-Based Systems
- Temperature Compensated Over -40° to +125°C
- Thermoplastic (PPS) Surface Mount Package
- Patented Silicon Shear Stress Strain Gauge
- Available in Differential and Gauge Configurations

## MP3V5010 Series

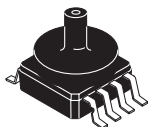
0 to 10 kPa (0 to 1.45 psi)  
0.1 to 3.1 V Output

### Application Examples

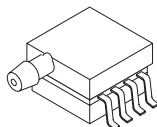
- Hospital Beds
- HVAC
- Respiratory Systems
- Process Control

ORDERING INFORMATION									
Device Name	Package Options	Case No.	# of Ports			Pressure Type			Device Marking
			None	Single	Dual	Gauge	Differential	Absolute	
<b>Small Outline Package (MP3V5010 Series)</b>									
MP3V5010GC6U	Rails	482A		•		•			MP3V5010G
MP3V5010GC6T1	Tape & Reel	482A		•		•			MP3V5010G
MP3V5010GP	Trays	1369		•		•			MP3V5010GP
MP3V5010DP	Trays	1351			•		•		MP3V5010DP
MP3V5010GVP	Trays	1368		•		•			MP3V5010GVP

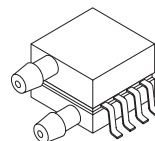
### SMALL OUTLINE PACKAGE



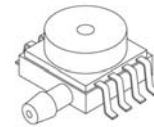
MP3V5010GC6U/C6T1  
CASE 482A-01



MP3V5010GP  
CASE 1369-01



MP3V5010DP  
CASE 1351-01



MP3V5010GVP  
CASE 1368-01

## Operating Characteristics

**Table 1. Operating Characteristics** ( $V_S = 3.0$  Vdc,  $T_A = 25^\circ\text{C}$  unless otherwise noted,  $P_1 > P_2$ . Decoupling circuit shown in Figure 3 required to meet specification.)

Characteristic	Symbol	Min	Typ	Max	Unit
Pressure Range <sup>(1)</sup>	$P_{OP}$	0	—	10	kPa
Supply Voltage <sup>(2)</sup>	$V_S$	2.7	3.0	3.3	Vdc
Supply Current	$I_o$	—	7.0	10	mAdc
Minimum Pressure Offset <sup>(3)</sup> @ $V_S = 3.0$ Volts	$V_{off}$	0.1	0.24	0.38	Vdc
Full Scale Output <sup>(4)</sup> @ $V_S = 3.0$ Volts	$V_{FSO}$	2.81	2.94	3.08	Vdc
Full Scale Span <sup>(5)</sup> @ $V_S = 3.0$ Volts	$V_{FSS}$	—	2.7	—	Vdc
Accuracy <sup>(6)</sup>	—	—	—	$\pm 5.0$	$\%V_{FSS}$
Sensitivity	V/P	—	270	—	mV/kPa
Response Time <sup>(7)</sup>	$t_R$	—	1.0	—	ms
Output Source Current at Full Scale Output	$I_{O+}$	—	0.1	—	mAdc
Warm-Up Time <sup>(8)</sup>	—	—	20	—	ms
Offset Stability <sup>(9)</sup>	—	—	$\pm 0.5$	—	$\%V_{FSS}$

- 1.0 kPa (kiloPascal) equals 0.145 psi.
- Device is ratiometric within this specified excitation range.
- Offset ( $V_{off}$ ) is defined as the output voltage at the minimum rated pressure.
- Full Scale Output ( $V_{FSO}$ ) is defined as the output voltage at the maximum or full rated pressure.
- Full Scale Span ( $V_{FSS}$ ) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
- Accuracy (error budget) consists of the following:
  - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
  - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
  - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at  $25^\circ\text{C}$ .
  - TcSpan: Output deviation over the temperature range of  $0^\circ$  to  $85^\circ\text{C}$ , relative to  $25^\circ\text{C}$ .
  - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of  $0^\circ$  to  $85^\circ\text{C}$ , relative to  $25^\circ\text{C}$ .
  - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of  $V_{FSS}$ , at  $25^\circ\text{C}$ .
- Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
- Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
- Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

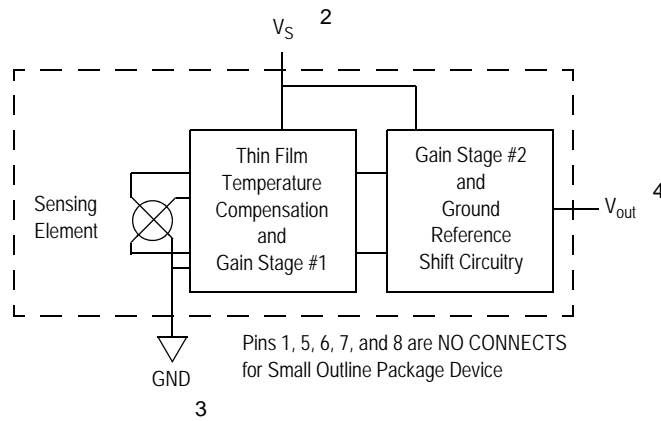
## Maximum Ratings

**Table 2. Maximum Ratings<sup>(1)</sup>**

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	$P_{max}$	75	kPa
Storage Temperature	$T_{stg}$	-40 to +125	°C
Operating Temperature	$T_A$	-40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.



**Figure 1. Integrated Pressure Sensor Schematic**

## ON-CHIP TEMPERATURE COMPENSATION, CALIBRATION AND SIGNAL CONDITIONING

The performance over temperature is achieved by integrating the shear-stress strain gauge, temperature compensation, calibration and signal conditioning circuitry onto a single monolithic chip.

Figure 2 illustrates the Differential or Gauge configuration in the basic chip carrier (Case 482). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm.

The MP3V5010 series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor

performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 3 shows the recommended decoupling circuit for interfacing the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

Figure 4 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 3. The output will saturate outside of the specified pressure range.

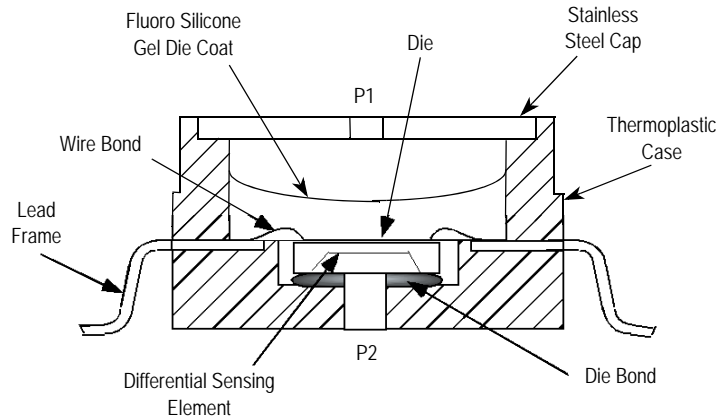


Figure 2. Cross-Sectional Diagram SOP (not to scale)

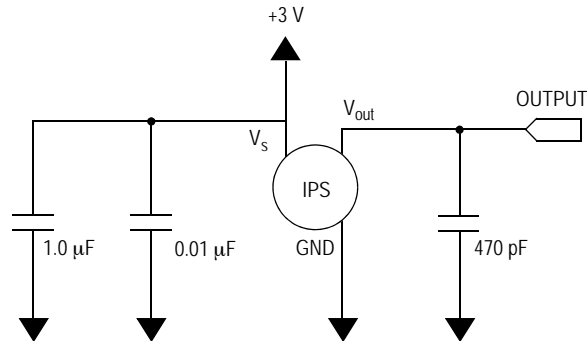


Figure 3. Recommended Power Supply Decoupling and Output Filtering (For additional output filtering, please refer to Application Note AN1646.)

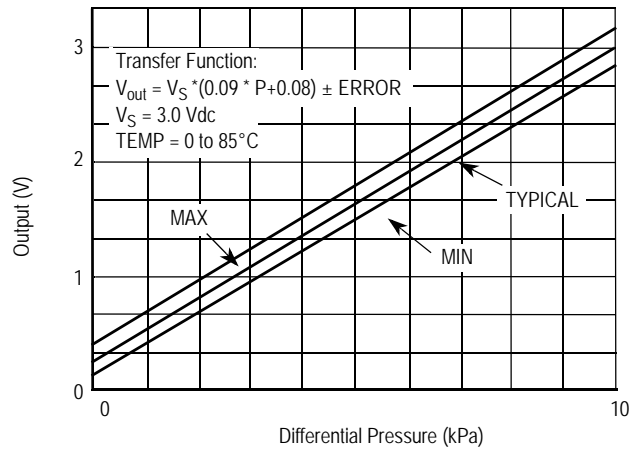


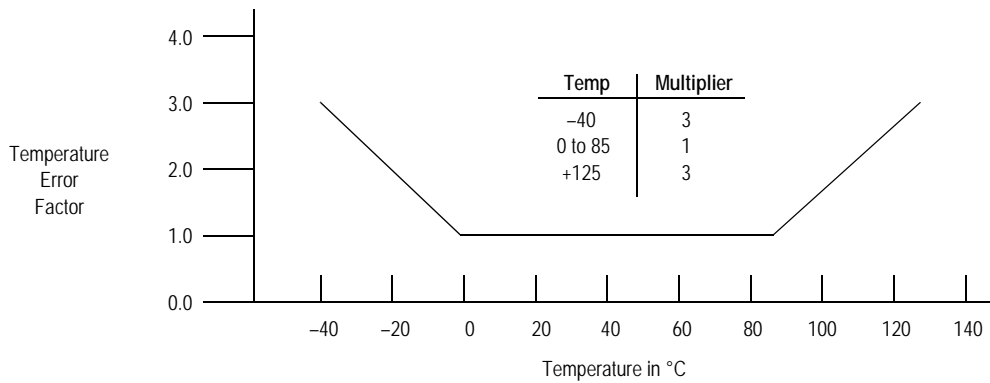
Figure 4. Output versus Pressure Differential

Transfer Function

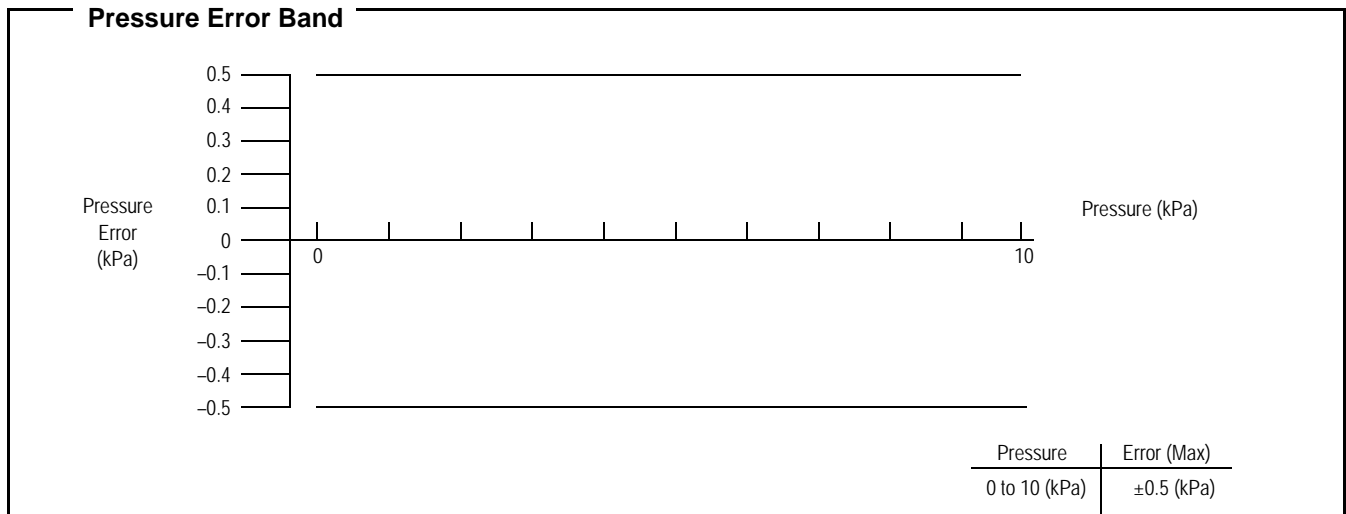
**Nominal Transfer Value:**  $V_{out} = V_S \times (0.09 \times P + 0.08)$   
 $\pm (\text{Pressure Error} \times \text{Temp. Factor} \times 0.09 \times V_S)$   
 $V_S = 3.0 \text{ V} \pm 0.30 \text{ Vdc}$

Temperature Error Band

MP3V5010 SERIES



NOTE: The Temperature Multiplier is a linear response from 0° to -40°C and from 85° to 125°C.



## PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

Freescale designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing fluoro silicone gel which protects the die from harsh media. The pressure

sensor is designed to operate with positive differential pressure applied,  $P1 > P2$ .

The Pressure (P1) side may be identified by using the following table:

Part Number	Case Type	Pressure (P1) Side Identifier
MP3V5010GC6U/C6T1	482A	Side with Port Attached
MP3V5010GP	1369	Side with Port Attached
MP3V5010DP	1351	Side with Part Marking
MP3V5010GVP	1368	Side with Part Marking

## MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the surface mount packages must be the correct size to ensure proper solder connection interface between the board and the package. With the correct

footprint, the packages will self align when subjected to a solder reflow process. It is always recommended to design boards with a solder mask layer to avoid bridging and shorting between solder pads.

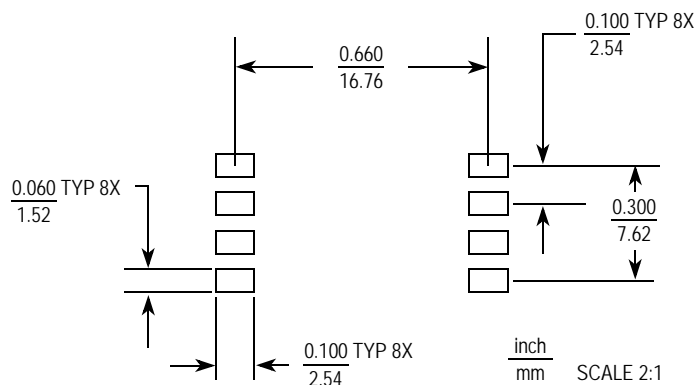
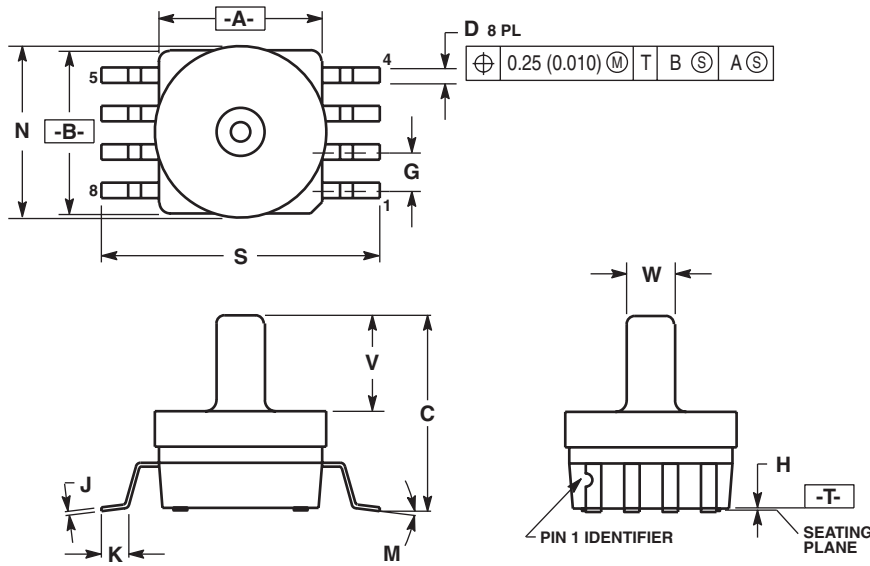


Figure 5. Small Outline Package Footprint

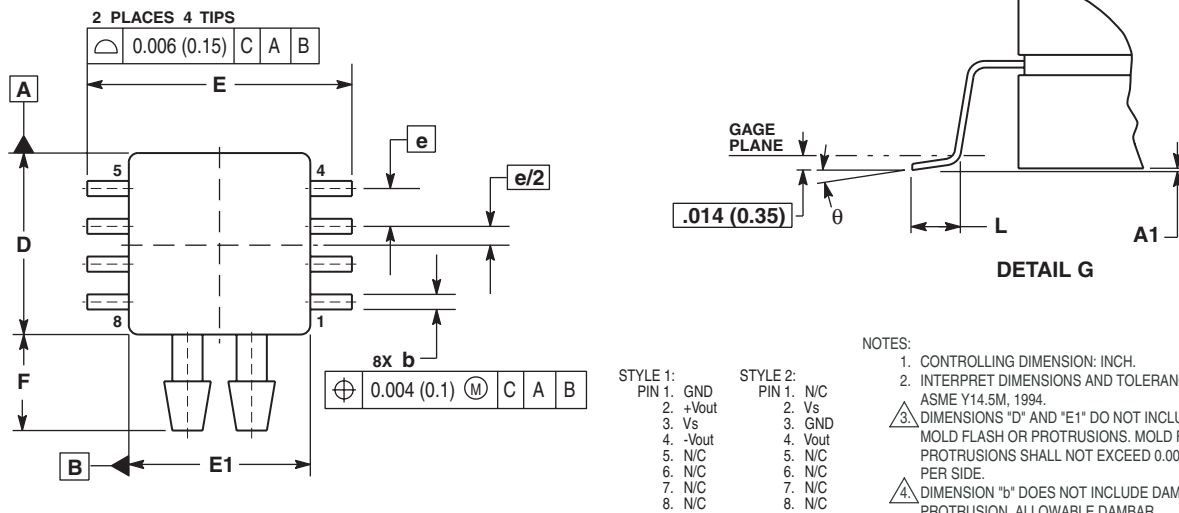
PACKAGE DIMENSIONS



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
  5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.415	0.425	10.54	10.79
B	0.415	0.425	10.54	10.79
C	0.500	0.520	12.70	13.21
D	0.038	0.042	0.96	1.07
G	0.100 BSC		2.54 BSC	
H	0.002	0.010	0.05	0.25
J	0.009	0.011	0.23	0.28
K	0.061	0.071	1.55	1.80
M	0"	7"	0"	7"
N	0.444	0.448	11.28	11.38
S	0.709	0.725	18.01	18.41
V	0.245	0.255	6.22	6.48
W	0.115	0.125	2.92	3.17

CASE 482A-01  
ISSUE A  
SMALL OUTLINE PACKAGE

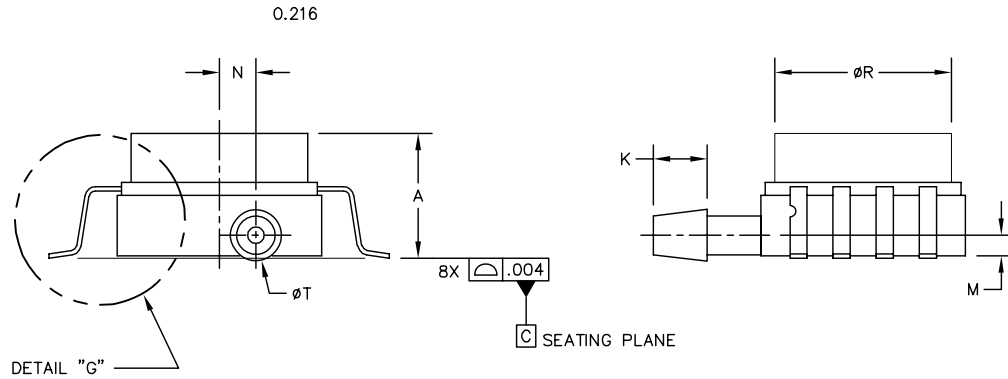
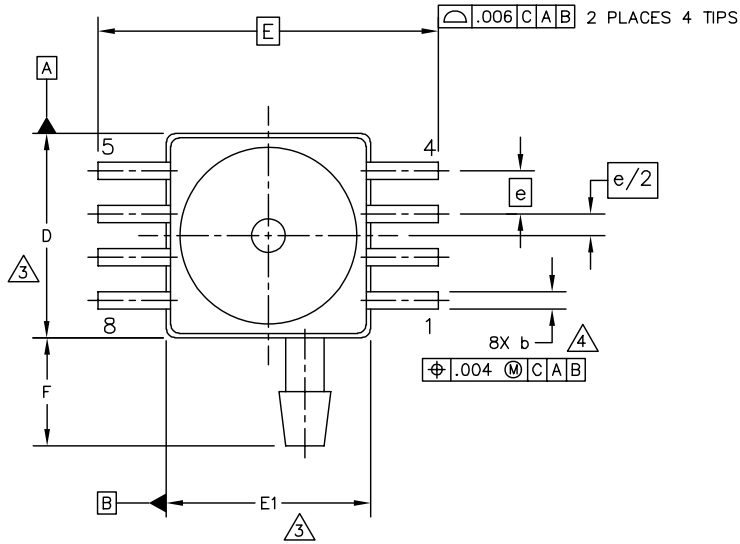


- NOTES:
1. CONTROLLING DIMENSION: INCH.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 (0.152) PER SIDE.
  4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.008 (0.203) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.370	0.390	9.39	9.91
A1	0.002	0.010	0.05	0.25
b	0.038	0.042	0.96	1.07
D	0.465	0.485	11.81	12.32
E	0.680	0.700	17.27	17.78
E1	0.465	0.485	11.81	12.32
e	0.100 BSC		2.54 BSC	
F	0.240	0.260	6.10	6.60
K	0.115	0.135	2.92	3.43
L	0.040	0.060	1.02	1.52
M	0.270	0.290	6.86	7.37
N	0.160	0.180	4.06	4.57
P	0.009	0.011	0.23	0.28
T	0.110	0.130	2.79	3.30
$\theta$	0"	7"	0"	7"

CASE 1351-01  
ISSUE O  
SMALL OUTLINE PACKAGE

PACKAGE DIMENSIONS

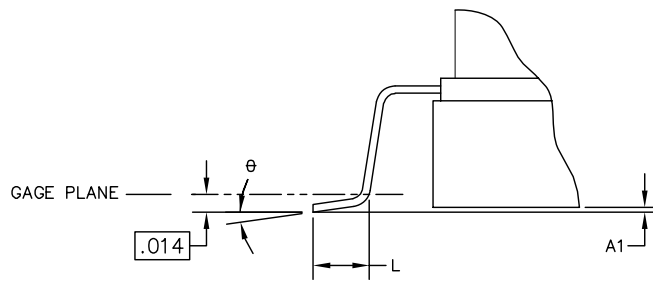


© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.  TITLE:  8 LD SOP, GVP	<b>MECHANICAL OUTLINE</b>		PRINT VERSION NOT TO SCALE	
	DOCUMENT NO: 98ASA99302D		REV: C	
	CASE NUMBER: 1368-01		18 DEC 2008	
	STANDARD: NON-JEDEC			

**CASE 1368-01  
ISSUE C  
SMALL OUTLINE PACKAGE**



PACKAGE DIMENSIONS



DETAIL "G"

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE:  8 LD SOP, GVP	DOCUMENT NO: 98ASA99302D	REV: C	
	CASE NUMBER: 1368-01	18 DEC 2008	
	STANDARD: NON-JEDEC		

**CASE 1368-01  
ISSUE C  
SMALL OUTLINE PACKAGE**

**PACKAGE DIMENSIONS**

NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. THIS DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.

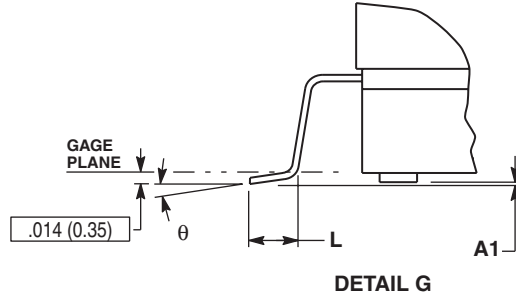
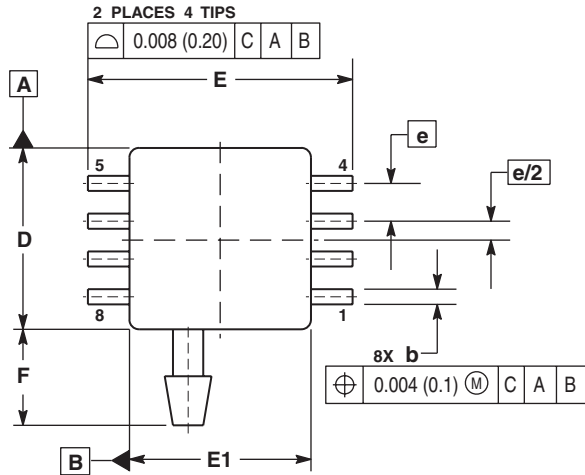
4. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

STYLE 1:	STYLE 2:
PIN 1: GND	PIN 1: N/C
PIN 2: +Vout	PIN 2: Vs
PIN 3: Vs	PIN 3: GND
PIN 4: -Vout	PIN 4: Vout
PIN 5: N/C	PIN 5: N/C
PIN 6: N/C	PIN 6: N/C
PIN 7: N/C	PIN 7: N/C
PIN 8: N/C	PIN 8: N/C

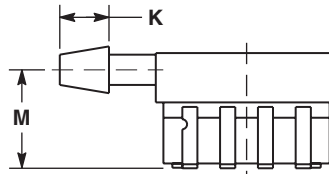
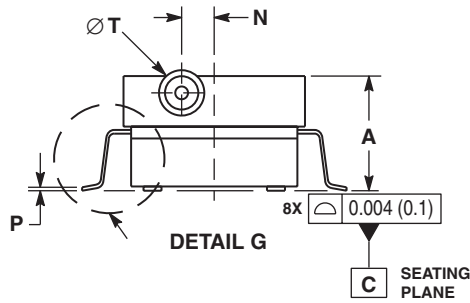
DIM	INCHES		MILLIMETERS		DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.280	.300	7.11	7.62	R	.405	.415	10.28	10.54
A1	.002	.010	0.05	0.25	θ	0°	7°	0°	7°
b	.038	.042	0.96	1.07	-	---	---	---	---
D	.465	.485	11.81	12.32	-	---	---	---	---
E	.690 BSC		17.52 BSC		-	---	---	---	---
E1	.465	.485	11.81	12.32	-	---	---	---	---
e	.100 BSC		2.54 BSC		-	---	---	---	---
F	.240	.260	6.10	6.60	-	---	---	---	---
K	.115	.135	2.92	3.43	-	---	---	---	---
L	.040	.060	1.02	1.52	-	---	---	---	---
M	.035	.055	0.89	1.39	-	---	---	---	---
N	.075	.095	1.90	2.41	-	---	---	---	---
P	.009	.011	0.23	0.28	-	---	---	---	---
T	.110	.130	2.79	3.30	-	---	---	---	---
© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.			<b>MECHANICAL OUTLINE</b>			PRINT VERSION NOT TO SCALE			
TITLE:  8 LD SOP, GVP					DOCUMENT NO: 98ASA99302D			REV: C	
					CASE NUMBER: 1368-01			18 DEC 2008	
					STANDARD: NON-JEDEC				

**CASE 1368-01  
ISSUE C  
SMALL OUTLINE PACKAGE**

PACKAGE DIMENSIONS



- NOTES:
1. CONTROLLING DIMENSION: INCH.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 (0.152) PER SIDE.
  4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.008 (0.203) MAXIMUM.



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.300	0.330	7.11	7.62
A1	0.002	0.010	0.05	0.25
b	0.038	0.042	0.96	1.07
D	0.465	0.485	11.81	12.32
E	0.717 BSC		18.21 BSC	
E1	0.465	0.485	11.81	12.32
e	0.100 BSC		2.54 BSC	
F	0.245	0.255	6.22	6.47
K	0.120	0.130	3.05	3.30
L	0.061	0.071	1.55	1.80
M	0.270	0.290	6.86	7.36
N	0.080	0.090	2.03	2.28
P	0.009	0.011	0.23	0.28
T	0.115	0.125	2.92	3.17
$\theta$	0°	7°	0°	7°

CASE 1369-01  
 ISSUE O  
 SMALL OUTLINE PACKAGE

## **How to Reach Us:**

### **Home Page:**

[www.freescale.com](http://www.freescale.com)

### **Web Support:**

<http://www.freescale.com/support>

### **USA/Europe or Locations Not Listed:**

Freescale Semiconductor, Inc.  
Technical Information Center, EL516  
2100 East Elliot Road  
Tempe, Arizona 85284  
1-800-521-6274 or +1-480-768-2130  
[www.freescale.com/support](http://www.freescale.com/support)

### **Europe, Middle East, and Africa:**

Freescale Halbleiter Deutschland GmbH  
Technical Information Center  
Schatzbogen 7  
81829 Muenchen, Germany  
+44 1296 380 456 (English)  
+46 8 52200080 (English)  
+49 89 92103 559 (German)  
+33 1 69 35 48 48 (French)  
[www.freescale.com/support](http://www.freescale.com/support)

### **Japan:**

Freescale Semiconductor Japan Ltd.  
Headquarters  
ARCO Tower 15F  
1-8-1, Shimo-Meguro, Meguro-ku,  
Tokyo 153-0064  
Japan  
0120 191014 or +81 3 5437 9125  
[support.japan@freescale.com](mailto:support.japan@freescale.com)

### **Asia/Pacific:**

Freescale Semiconductor China Ltd.  
Exchange Building 23F  
No. 118 Jianguo Road  
Chaoyang District  
Beijing 100022  
China  
+86 010 5879 8000  
[support.asia@freescale.com](mailto:support.asia@freescale.com)

### **For Literature Requests Only:**

Freescale Semiconductor Literature Distribution Center  
1-800-441-2447 or +1-303-675-2140  
Fax: +1-303-675-2150  
[LDCForFreescaleSemiconductor@hibbertgroup.com](mailto:LDCForFreescaleSemiconductor@hibbertgroup.com)

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© Freescale Semiconductor, Inc. 2009. All rights reserved.

